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Substitute for form 1449A/PTO	Complete if Known		
INFORMATION DISCLOSURE	Application Number	10/623788	
STATEMENT BY APPLICANT (Use as many sheets as necessary) P E	Filing Date	July 21, 2003	
(O) CE	First Named Inventor	Forbes, Leonard	
MAY 1 2 2004 E	Group Art Unit	2811	
	Examiner Name	Unknown	
Sheet 1 of 7	Attorney Docket No: 1	303.109US1	

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	First Named Inventor	Forbes, Leonard			
	Group Art Unit	2811			
	Examiner Name	Unknown			
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,	First Named Inventor	Forbes, Leonard			
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Sheet 5 of 7	Attorney Docket No: 1	303.109US1			

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	Group Art Unit	2811	
	Examiner Name	Unknown	
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